

	Type	Hits	Search Text	DBs
1	BRS	1981	("chip on chip" or stack\$ adj (chip or die or IC or semiconductor))	USPAT; JPO
2	BRS	15882	(chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$)	USPAT; JPO
3	BRS	3898	(chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold)	USPAT; JPO
4	BRS	1538	257/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold)	USPAT; JPO
5	BRS	397	438/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold) not (257/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold))	USPAT; JPO

	Type	Hits	Search Text	DBs
6	BRS	209	361/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold) not ((257/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold)) or (438/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold) not (257/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold))))	USPAT; JPO
7	BRS	1538	257/\$.ccls. and (chip or die or semiconduct\$ adj device) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold)	USPAT; JPO
8	BRS	79	4264917.uref.	USPAT; JPO
9	BRS	160	("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire and external with (electrodes or connect\$) and (encapsul\$ or mold)	USPAT; JPO
10	BRS	297	("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire and (electrodes or connect\$) and (encapsul\$ or mold)	USPAT; JPO
11	BRS	5	("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire and (encapsul\$ or mold) not (("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire and (electrodes or connect\$) and (encapsul\$ or mold))	USPAT; JPO

	Type	Hits	Search Text	DBs
12	BRS	444	("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire not (("chip on chip" or stack\$ adj (chip or die or IC or semiconductor)) and wire and (electrodes or connect\$) and (encapsul\$ or mold))	USPAT; JPO
13	BRS	1	03169062.pn.	USPAT; JPO
14	BRS	12	03169062.pn. or 05013611.pn. or 03094430.pn. or 6005778.pn. or 6014586.pn. or 6133629.pn. or 6198171.pn. or 5900676.pn. or 5349233.pn. or 6246115.pn. or 5239198.pn. or 5096852.pn.	USPAT; JPO
15	BRS	15	03169062.pn. or 05013611.pn. or 03094430.pn. or 6005778.pn. or 6014586.pn. or 6133629.pn. or 6198171.pn. or 5900676.pn. or 5349233.pn. or 6246115.pn. or 5239198.pn. or 5096852.pn. or 4264917.pn. or 5273938.pn. or 11204720.pn.	USPAT; JPO
16	BRS	1767	(257/666 or 257/685 or 257/686 or 257/687 or 257/688) and (chip or die or semiconduct\$ adj device) and wire and (electrodes or connect\$ or terminal) and (encapsul\$ or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
17	BRS	248	(257/666 or 257/685 or 257/686 or 257/687 or 257/688) and multi\$ adj (chip or die or semiconduct\$ adj device) and wire and (electrodes or connect\$ or terminal) and (encapsul\$ or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
18	BRS	258	(257/689 or 257/710 or 257/723 or 257/724 or 257/777) and multi\$ adj (chip or die or semiconduct\$ adj device) and wire and (electrodes or connect\$ or terminal) and (encapsul\$ or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
19	BRS	163	(257/778 or 257/779 or 257/780 or 257/781 or 257/782) and multi\$ adj (chip or die or semiconduct\$ adj device) and wire and (electrodes or connect\$ or terminal) and (encapsul\$ or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
20	BRS	176	(257/783 or 257/784 or 257/785 or 257/786 or 257/787) and multi\$ adj (chip or die or semiconduct\$ adj device) and wire and (electrodes or connect\$ or terminal) and (encapsul\$ or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB